

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	HEAT SPREADER ANCHORING AND GROUNDING METHOD AND THERMALLY ENHANCED PBGA PACKAGE USING THE SAME	
Application Type: regular, utility Attorney Docket Number: 27-026.D1		
Correspondence address: <div style="display: flex; justify-content: space-between;"> Customer Number: 22898 *22898* </div>		
Continuing Data: This is a Division of US application number 10/055,094, filed 2002-01-23 , now pending.		
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Publication Information:

Suggested Figure for Publication – FIG. 7g

Suggested Classification –

Suggested Technology Center –
Total Number of Drawing Sheets – 8

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